



PTO/SB/30 (10/2001)

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REQUEST

FOR

**CONTINUED EXAMINATION (RCE)
TRANSMITTAL**

Address to:
Commissioner for Patents
Box RCE
Washington, DC 20231

Application Number **09/045,507**Filing Date **March 20, 1998**First Named Inventor **Donald Malcolm MacIntyre**Art Unit **2814**Examiner Name **D. Wille**Attorney Docket Number **MICSP-101****This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application**

Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See Instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.

1. Submission required under 37 CFR §1.114

a. Previously submitted

- i. Consider the amendment(s)/reply under 37 CFR §1.116 previously filed on _____
(Any unentered amendment(s) referred to above will be entered).
- ii. Consider the arguments in the Appeal Brief or Reply Brief previously filed on _____
- iii. Other _____

b. Enclosed

- i. Amendment/Reply iii. Information Disclosure Statement (IDS)
- ii. Affidavit(s)/Declaration(s) iv. Other _____

2. Miscellaneous

a. Suspension of action on the above-identified application is requested under 37 CFR §1.103(c) for a period of _____ months (Period of suspension shall not exceed 3 months; Fee under 37 CFR §1.17(i) required)

b. Other

3. Fees The RCE fee under 37 CFR §1.17(e) is required by 37 CFR §1.114 when the RCE is filed.

a. The Director is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. **50-1703**

- i. RCE fee required under 37 CFR §1.17(e)
- ii. Extension of time fee (37 CFR §§1.136 and 1.17)
- iii. Other _____

b. Check in the amount of \$ **840.00** enclosed

c. Payment by credit card (Form PTO-2038 enclosed)

WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT REQUIRED

Name / Print / Type:	Michael J. Pollock	Registration No. / Attorney / Agent:	29,098
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Signature

Date **January 29, 2003****CERTIFICATE OF MAILING OR TRANSMISSION**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner For Patents Box RCE Washington DC 20231 or facsimile transmitted to the U S Patent

Burden Hour Statement: This form is estimated to take 0.2 hours to complete. Time will vary depending upon the needs of the individual case. Any comments or the amount of time you are required to complete this form should be sent to the Chief Information Officer, U S Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND FEES and Completed Forms to the following address: Assistant Commissioner for Patents, Box RCE, Washington, DC 20231.



STALLMAN & POLLOCK LLP

121 Spear Street, Suite 290
San Francisco, CA 94105
(415) 512-1312

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Atty. Docket No. MCSP-101

In re Patent Application of: Donald Malcolm MacIntyre

TECH 1

Application No.: 09 045,507

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmittal herewith is an amendment in the above-identified application.

The fee has been calculated as shown below.

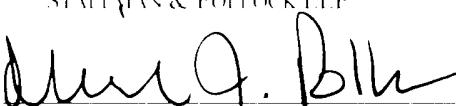
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	10	MINUS	20	0	x \$18 =	\$0
INDEP.	3	MINUS	3	0	x \$84 =	\$0
FIRST PRESENTATION OF MULTIPLE DEP CLAIMS					+ \$280	\$0
					TOTAL	\$0

Small Entity 50% Filing Fee Reduction (if applicable) \$0

* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3
** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
*** If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent is the highest number found from the equivalent box in Col. 1 of a prior amendment or the number of claims originally filed.)

- Enclosed for filing a Request for Continued Examination.
- Applicant(s) hereby petition(s) for a three-month extension of time in which to file the present response and enclose(s) herewith the necessary fee to accompany this petition. A check in the amount of \$840.00 is attached (total for RCE fee of \$375.00, & 3-month extension of \$465.00).
- Please charge any additional fees, including any fees necessary for extensions of time or credit overpayment to Deposit Account No. 50-1703, under Order No. MCSP-101.
A duplicate copy of this sheet is enclosed.

Dated: January 29, 2003

By: 
Michael J. Pollock (Reg. No. 29,098)
Attorneys for Applicant(s)

CERTIFICATE OF MAILING

I declare under penalty of perjury that the above instrument was sent by United States Postal Service as first class mail.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Group Art Unit: 2814

Donald Malcolm MacIntyre

Examiner: D. Wille

Application No.: 09/045,507

RESPONSE TO FINAL REJECTION
MAILED JULY 25, 2002

Filed: March 20, 1998

For: CHIP SCALE PACKAGES

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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope, addressed to: Commissioner for Patents, Washington, DC 20231 on January 24, 2003.

STALLMAN & POLLOCK LLP

Dated: 01/24/2003 By: Georgia K. Stith
 Georgia K. Stith

Sir:

Please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 59-67 and add the following new claims:

→68. (New) A semiconductor integrated circuit wafer scale structure comprising:
 a semiconductor wafer substrate that includes a plurality of semiconductor integrated circuit die formed on an upper surface of the wafer substrate, each individual semiconductor integrated circuit die including a plurality of conductive die bond pads formed on an upper surface of said integrated circuit die;